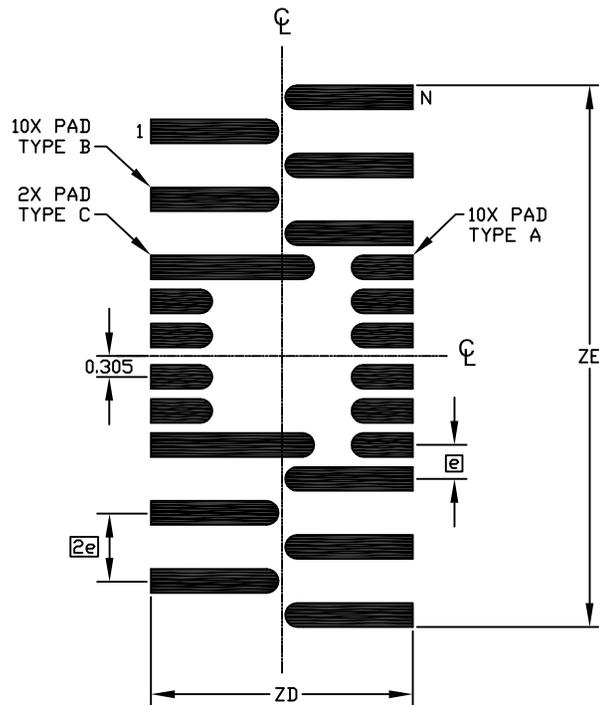
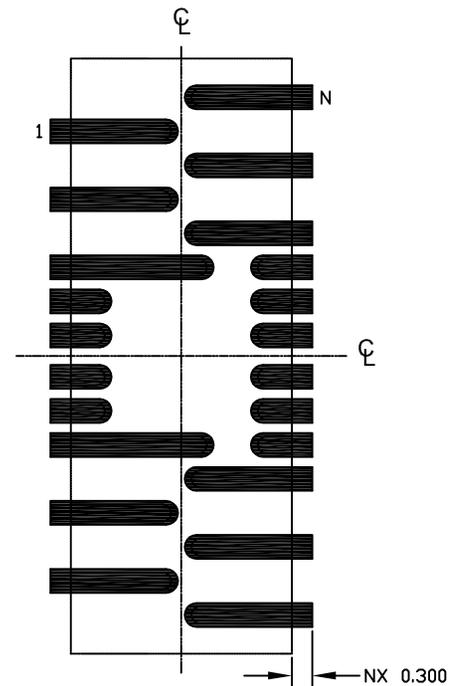


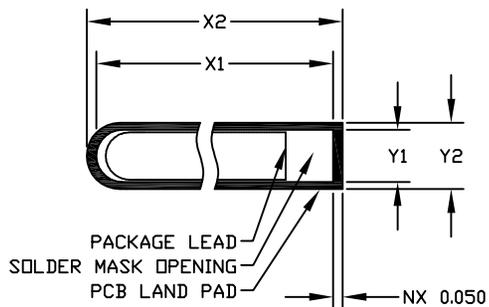
RECOMMENDED LAND PATTERN



PACKAGE OVERLAY



PAD DETAIL INFORMATION



DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
e	0.500 BSC			.020 BSC		
N	22 PINS			22 PINS		
ZD	3.850 REF			.152 REF		
ZE	7.960 REF			.313 REF		

DIM	MILLIMETERS			INCHES		
	TYPE A	TYPE B	TYPE C	TYPE A	TYPE B	TYPE C
Y1	0.275	0.275	0.275	.011	.011	.011
Y2	0.350	0.350	0.350	.014	.014	.014
X1	0.800	1.775	2.300	.031	.070	.091
X2	0.900	1.875	2.400	.035	.074	.094

NOTES:

1. REFERENCE PKG. OUTLINE: 21-1020
2. LAND PATTERN COMPLIES TO: IPC7351A.
3. ALL DIMENSIONS APPLY TO PbFREE (+) PKG. CODE ONLY.
4. ALL DIMENSIONS IN MM.

—DRAWING NOT TO SCALE—



TITLE:  
PACKAGE LAND PATTERN,  
[P223B8F+1] FCQFN

APPROVAL

DOCUMENT CONTROL NO.

REV.

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This document (including dimensions, notes & specs) is a recommendation based on typical circuit board manufacturing parameters. Since land pattern design depend on many factors unknown to Maxim (eg. user's board manufacturing specs), user must determine suitability for use.

This document is subject to change without notice.

Contact technical support at <http://www.maximintegrated.com/support> for further questions.